

Youngwoo Kim

List of Publications by Year in descending order

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40
papers

546
citations

759233

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40
docs citations

40
times ranked

420
citing authors

#	ARTICLE	IF	CITATIONS
1	EMI Reduction Methods in Wireless Power Transfer System for Drone Electrical Charger Using Tightly Coupled Three-Phase Resonant Magnetic Field. IEEE Transactions on Industrial Electronics, 2018, 65, 6839-6849.	7.9	104
2	Deep Reinforcement Learning-Based Optimal Decoupling Capacitor Design Method for Silicon Interposer-Based 2.5-D/3-D ICs. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 467-478.	2.5	47
3	Signal Integrity Design and Analysis of Silicon Interposer for GPU-Memory Channels in High-Bandwidth Memory Interface. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 1658-1671.	2.5	40
4	Signal Integrity Design and Analysis of Differential High-Speed Serial Links in Silicon Interposer With Through-Silicon Via. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 107-121.	2.5	26
5	Design and Analysis of Power Distribution Network (PDN) for High Bandwidth Memory (HBM) Interposer in 2.5D Terabyte/s Bandwidth Graphics Module. , 2016, , .		24
6	Design optimization of high bandwidth memory (HBM) interposer considering signal integrity. , 2015, , .		21
7	Miniaturized Bandpass Filters as Ultrathin 3-D IPDs and Embedded Thinfilms in 3-D Glass Modules. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, 7, 1410-1418.	2.5	21
8	Fast and Accurate Power Distribution Network Modeling of a Silicon Interposer for 2.5-D/3-D ICs With Multiarray TSVs. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 1835-1846.	2.5	19
9	Measurement and Analysis of Glass Interposer Power Distribution Network Resonance Effects on a High-Speed Through Glass Via Channel. IEEE Transactions on Electromagnetic Compatibility, 2016, 58, 1747-1759.	2.2	18
10	A Frequency-Selective EMI Reduction Method for Tightly Coupled Wireless Power Transfer Systems Using Resonant Frequency Control of a Shielding Coil in Smartphone Application. IEEE Transactions on Electromagnetic Compatibility, 2019, 61, 2031-2039.	2.2	18
11	Highly-Effective Integrated EMI Shields with Graphene and Nanomagnetic Multilayered Composites. , 2016, , .		16
12	A Near Field Analytical Model for EMI Reduction and Efficiency Enhancement Using an n th Harmonic Frequency Shielding Coil in a Loosely Coupled Automotive WPT System. IEEE Transactions on Electromagnetic Compatibility, 2021, 63, 935-946.	2.2	15
13	Analysis of Power Distribution Network in glass, silicon interposer and PCB. , 2014, , .		13
14	Power distribution network (PDN) design and analysis of a single and double-sided high bandwidth memory (HBM) interposer for 2.5D Terabyte/s bandwidth system. , 2016, , .		13
15	A Novel Stochastic Model-Based Eye-Diagram Estimation Method for 8B/10B and TMD5-Encoded High-Speed Channels. IEEE Transactions on Electromagnetic Compatibility, 2018, 60, 1510-1519.	2.2	13
16	Design and Measurement of a Novel On-Interposer Active Power Distribution Network for Efficient Simultaneous Switching Noise Suppression in 2.5-D/3-D IC. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 317-328.	2.5	12
17	Polynomial Model-Based Eye Diagram Estimation Methods for LFSR-Based Bit Streams in PRBS Test and Scrambling. IEEE Transactions on Electromagnetic Compatibility, 2019, 61, 1867-1875.	2.2	12
18	Wideband Power/Ground Noise Suppression in Low-Loss Glass Interposers Using a Double-Sided Electromagnetic Bandgap Structure. IEEE Transactions on Microwave Theory and Techniques, 2020, 68, 5055-5064.	4.6	12

#	ARTICLE	IF	CITATIONS
19	Signal Integrity Design and Analysis of 3-D X-Point Memory Considering Crosstalk and IR Drop for Higher Performance Computing. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 858-869.	2.5	11
20	Channel Characteristic-Based Deep Neural Network Models for Accurate Eye Diagram Estimation in High Bandwidth Memory (HBM) Silicon Interposer. IEEE Transactions on Electromagnetic Compatibility, 2022, 64, 196-208.	2.2	11
21	Measurement and Analysis of Through Glass Via Noise Coupling and Shielding Structures in a Glass Interposer. IEEE Transactions on Electromagnetic Compatibility, 2021, 63, 1562-1573.	2.2	11
22	Signal Integrity and Computing Performance Analysis of a Processing-In-Memory of High Bandwidth Memory (PIM-HBM) Scheme. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 1955-1970.	2.5	10
23	Glass-Interposer Electromagnetic Bandgap Structure With Defected Ground Plane for Broadband Suppression of Power/Ground Noise Coupling. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, 7, 1493-1505.	2.5	9
24	A Novel Eye-Diagram Estimation Method for Pulse Amplitude Modulation With N -Level (PAM-N) on Stacked Through-Silicon Vias. IEEE Transactions on Electromagnetic Compatibility, 2019, 61, 1198-1206.	2.2	8
25	Statistical Eye-Diagram Estimation Method Considering Power/Ground Noise Induced by Simultaneous Switching Output (SSO) Buffers. IEEE Transactions on Electromagnetic Compatibility, 2020, 62, 2547-2557.	2.2	8
26	Measurement and Analysis of Electromagnetic Information Leakage From Printed Circuit Board Power Delivery Network of Cryptographic Devices. IEEE Transactions on Electromagnetic Compatibility, 2021, 63, 1322-1332.	2.2	7
27	Segmentation method based modeling and analysis of a glass package power distribution network (PDN). Nonlinear Theory and Its Applications IEICE, 2020, 11, 170-188.	0.6	5
28	Through-Silicon Via Capacitance Voltage Hysteresis Modeling for 2.5-D and 3-D IC. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, 7, 925-935.	2.5	4
29	Eye-Diagram Estimation Methods for Voltage-and Probability-Dependent PAM-4 Signal on Stacked Through-Silicon Vias (TSVs). , 2017, , .		4
30	Modeling, Measurement, and Analysis of Audio Frequency Ground Integrity for a TDMA Smartphone System. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 519-530.	2.5	4
31	Analysis of through glass via (TGV) noise coupling effect to noise figure of 2.4GHz LNA on glass interposer. , 2015, , .		3
32	Statistical Analysis of Simultaneous Switching Output (SSO) Impacts on Steady State Output Responses and Signal Integrity. , 2019, , .		3
33	Analysis of Electromagnetic Information Leakage from Overdesigned Power Delivery Network of Cryptographic Devices. , 2021, , .		3
34	Design and analysis of receiver channels of glass interposer for dual band Wi-Fi front end module (FEM). , 2017, , .		1
35	Electrical Performance Analysis of Glass Interposer Channel and Power Distribution Network. , 2018, , .		0
36	Efficient Electromagnetic Analysis Based on Side-channel Measurement Focusing on Physical Structures. , 2020, , .		0

#	ARTICLE	IF	CITATIONS
37	Statistical Analysis and Modeling of a High Bandwidth Memory (HBM) Interposer Channel. , 2020, , .		0
38	A Fundamental Evaluation of EM Information Leakage Induced by IEMI for a Device with Differential Signaling. , 2021, , .		0
39	Analysis of Filtering Window Impacts on Estimation Accuracy of Information Leakage from Exposed Power Delivery Network of Cryptographic Devices. , 2022, , .		0
40	A Novel FDTD Approach Considering Frequency Dispersion of FR-4 Substrates for Signal Transmission Analyses at GHz Band. IEEE Transactions on Electromagnetic Compatibility, 2022, , 1-11.	2.2	0